



Material Content Data Sheet



Sales Product Name	IPB160N04S4-02D			Issued		29. August 2013		
MA#	MA001141932							
Package	PG-TO263-7-3			Weight*		1520.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.217	0.08		800	
	noble metal	gold	7440-57-5	0.233	0.02		153	
	non noble metal	tin	7440-31-5	0.060	0.00	0.10	39	992
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		528	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	copper	7440-50-8	801.714	52.72	52.79	527256	527943
wire	non noble metal	aluminium	7429-90-5	10.135	0.67	0.67	6665	6665
encapsulation	organic material	carbon black	1333-86-4	8.808	0.58		5793	
	plastics	epoxy resin	-	96.889	6.37		63720	
	inorganic material	silicondioxide	60676-86-0	481.508	31.67	38.62	316669	386182
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8100	8100
plating	non noble metal	nickel	7440-02-0	0.269	0.02		177	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	177
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		70	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.98	6.99	69850	69941
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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